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Details

201010	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	64 x 8
RAM Size	68 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f84-04-p

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Name	DIP No.	SOIC No.	l/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	16	Ι	ST/CMOS (3)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	0		Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR	4	4	I/P	ST	Master clear (reset) input/programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0	17	17	I/O	TTL	
RA1	18	18	I/O	TTL	
RA2	1	1	I/O	TTL	
RA3	2	2	I/O	TTL	
RA4/T0CKI	3	3	I/O	ST	Can also be selected to be the clock input to the TMR0 timer/ counter. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software pro- grammed for internal weak pull-up on all inputs.
RB0/INT	6	6	I/O	TTL/ST ⁽¹⁾	RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	I/O	TTL	
RB2	8	8	I/O	TTL	
RB3	9	9	I/O	TTL	
RB4	10	10	I/O	TTL	Interrupt on change pin.
RB5	11	11	I/O	TTL	Interrupt on change pin.
RB6	12	12	I/O	TTL/ST ⁽²⁾	Interrupt on change pin. Serial programming clock.
RB7	13	13	I/O	TTL/ST (2)	Interrupt on change pin. Serial programming data.
Vss	5	5	Р	—	Ground reference for logic and I/O pins.
Vdd	14	14	Р	—	Positive supply for logic and I/O pins.
Legend: I= input	0 = 0 — = N	utput lot used		/O = Input/Out	•

TABLE 3-1 PIC16F8X PINOUT DESCRIPTION

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in serial programming mode.

3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

4.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC16F8X. These are the program memory and the data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into the general purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the "core" are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

The data memory area also contains the data EEPROM memory. This memory is not directly mapped into the data memory, but is indirectly mapped. That is, an indirect address pointer specifies the address of the data EEPROM memory to read/write. The 64 bytes of data EEPROM memory have the address range 0h-3Fh. More details on the EEPROM memory can be found in Section 7.0.

4.1 Program Memory Organization

The PIC16FXX has a 13-bit program counter capable of addressing an 8K x 14 program memory space. For the PIC16F83 and PIC16CR83, the first 512 x 14 (0000h-01FFh) are physically implemented (Figure 4-1). For the PIC16F84 and PIC16CR84, the first 1K x 14 (0000h-03FFh) are physically implemented (Figure 4-2). Accessing a location above the physically implemented address will cause a wraparound. For example, for the PIC16F84 locations 20h, 420h, 820h, C20h, 1020h, 1420h, 1820h, and 1C20h will be the same instruction.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK-PIC16F83/CR83

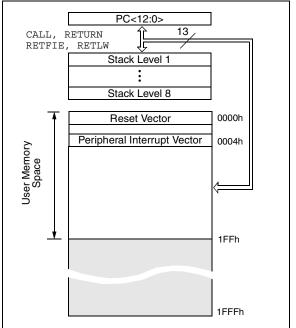
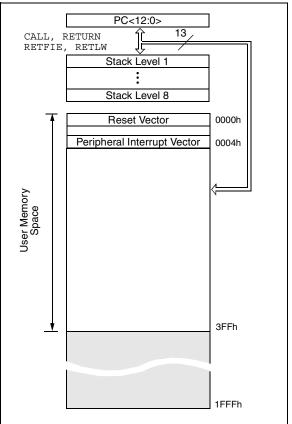


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK - PIC16F84/CR84



5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch is unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (i.e., BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output current may damage the chip.

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-5). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such that the pin voltage stabilizes (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

Example 5-1 shows the effect of two sequential read-modify-write instructions (e.g., ${\tt BCF}\,,\,\,{\tt BSF},\, etc.)$ on an I/O port.

EXAMPLE 5-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

;Initial PORT settings: PORTB<7:4> Inputs ; PORTB<3:0> Outputs ;PORTB<7:6> have external pull-ups and are ;not connected to other circuitry

'								
;					PORT	latch	PORT	pins
;								
	BCF	PORTB,	7	;	01pp	ppp	11pp	ppp
	BCF	PORTB,	6	;	10pp	ppp	11pp	ppp
	BSF	STATUS	, RPO	;				
	BCF	TRISB,	7	;	10pp	ppp	11pp	ppp
	BCF	TRISB,	6	;	10pp	ppp	10pp	ppp
:								

;Note that the user may have expected the ;pin values to be 00pp ppp. The 2nd BCF ;caused RB7 to be latched as the pin value ;(high).

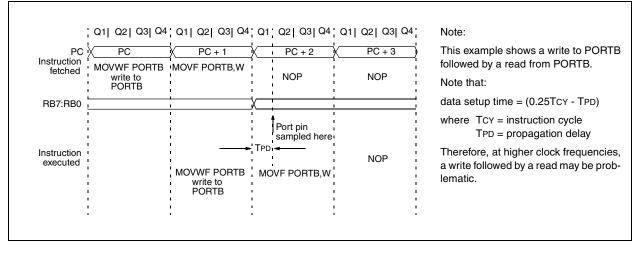


FIGURE 5-5: SUCCESSIVE I/O OPERATION

PIC16F8X

NOTES:

7.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full VDD range). This memory is not directly mapped in the register file space. Instead it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory. These registers are:

- EECON1
- EECON2
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F8X devices have 64 bytes of data EEPROM with an address range from 0h to 3Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The writetime will vary with voltage and temperature as well as from chip to chip. Please refer to AC specifications for exact limits.

When the device is code protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

7.1 <u>EEADR</u>

The EEADR register can address up to a maximum of 256 bytes of data EEPROM. Only the first 64 bytes of data EEPROM are implemented.

The upper two bits are address decoded. This means that these two bits must always be '0' to ensure that the address is in the 64 byte memory space.

U	U	U	R/W-0	R/W-x	R/W-0	R/S-0	R/S-x			
_	_		EEIF	WRERR	WREN	WR	RD	R = Readable bit		
bit7							bitO	W = Writable bit S = Settable bit U = Unimplemented bit, read as '0' - n = Value at POR reset		
bit 7:5	Unimplem	nented: F	Read as '()'						
bit 4	1 = The w	rite opera	ation com	oleted (mus	upt Flag bit st be cleare or has not	ed in softw				
bit 3	 WRERR: EEPROM Error Flag bit 1 = A write operation is prematurely terminated (any MCLR reset or any WDT reset during normal operation) 0 = The write operation completed 									
bit 2	WREN: EF 1 = Allows 0 = Inhibits	write cyc	cles							
bit 1		s a write (not clea	cycle. (Ti red) in so	ftware.	-	ardware or	nce write is	complete. The WR bit can only		
bit 0		es an EEI (not clea	PROM rea red) in so	ftware).	kes one cy	cle. RD is	cleared in	hardware. The RD bit can only		

FIGURE 7-1: EECON1 REGISTER (ADDRESS 88h)

8.4 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, just tie the \overline{MCLR} pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A minimum rise time for VDD must be met for this to operate properly. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be meet to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting.*"

The POR circuit does not produce an internal reset when VDD declines.

8.5 Power-up Timer (PWRT)

The Power-up Timer (PWRT) provides a fixed 72 ms nominal time-out (TPWRT) from POR (Figure 8-10, Figure 8-11, Figure 8-12 and Figure 8-13). The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level (Possible exception shown in Figure 8-13).

A configuration bit, PWRTE, can enable/disable the PWRT. See either Figure 8-1 or Figure 8-2 for the operation of the PWRTE bit for a particular device.

The power-up time delay TPWRT will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

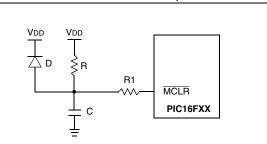
8.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle delay (from OSC1 input) after the PWRT delay ends (Figure 8-10, Figure 8-11, Figure 8-12 and Figure 8-13). This ensures the crystal oscillator or resonator has started and stabilized.

The OST time-out (TOST) is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

When VDD rises very slowly, it is possible that the TPWRT time-out and TOST time-out will expire before VDD has reached its final value. In this case (Figure 8-13), an external power-on reset circuit may be necessary (Figure 8-9).

FIGURE 8-9: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- Note 1: External Power-on Reset circuit is required only if VDD power-up rate is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
 - R < 40 kΩ is recommended to make sure that voltage drop across R does not exceed 0.2V (max leakage current spec on MCLR pin is 5 µA). A larger voltage drop will degrade VIH level on the MCLR pin.
 - 3: R1 = 100Ω to 1 k Ω will limit any current flowing into MCLR from external capacitor C in the event of an MCLR pin breakdown due to ESD or EOS.

8.7 <u>Time-out Sequence and Power-down</u> Status Bits (TO/PD)

On power-up (Figure 8-10, Figure 8-11, Figure 8-12 and Figure 8-13) the time-out sequence is as follows: First PWRT time-out is invoked after a POR has expired. Then the OST is activated. The total time-out will vary based on oscillator configuration and PWRTE configuration bit status. For example, in RC mode with the PWRT disabled, there will be no time-out at all.

TABLE 8-5TIME-OUT IN VARIOUSSITUATIONS

Oscillator	Powe	Power-up				
Configuration	PWRT Enabled	PWRT Disabled	from SLEEP			
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024Tosc			
RC	72 ms	_	_			

Since the time-outs occur from the POR reset pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high, execution will begin immediately (Figure 8-10). This is useful for testing purposes or to synchronize more than one PIC16F8X device when operating in parallel.

Table 8-6 shows the significance of the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits. Table 8-3 lists the reset conditions for some special registers, while Table 8-4 lists the reset conditions for all the registers.

TABLE 8-6STATUS BITS AND THEIRSIGNIFICANCE

то	PD	Condition
1	1	Power-on Reset
0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
x	0	Illegal, PD is set on POR
0	1	WDT Reset (during normal operation)
0	0	WDT Wake-up
1	1	MCLR Reset during normal operation
1	0	MCLR Reset during SLEEP or interrupt
		wake-up from SLEEP

8.8 Reset on Brown-Out

A brown-out is a condition where device power (VDD) dips below its minimum value, but not to zero, and then recovers. The device should be reset in the event of a brown-out.

To reset a PIC16F8X device when a brown-out occurs, external brown-out protection circuits may be built, as shown in Figure 8-14 and Figure 8-15.

FIGURE 8-14: BROWN-OUT PROTECTION CIRCUIT 1

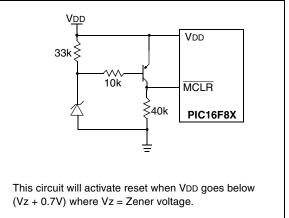
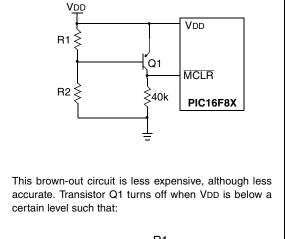


FIGURE 8-15: BROWN-OUT PROTECTION CIRCUIT 2



$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

8.11 Watchdog Timer (WDT)

The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT Wake-up causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming configuration bit WDTE as a '0' (Section 8.1).

8.11.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to

FIGURE 8-18: WATCHDOG TIMER BLOCK DIAGRAM

part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION_REG register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler (if assigned to the WDT) and prevent it from timing out and generating a device RESET condition.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a WDT time-out.

8.11.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

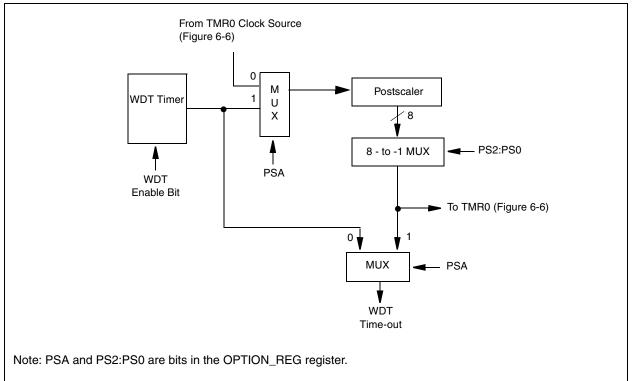


TABLE 8-7 SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets
2007h	Config. bits	(2)	(2)	(2)	(2)	PWRTE ⁽¹⁾	WDTE	FOSC1	FOSC0	(2)	
81h	OPTION_ REG	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown. Shaded cells are not used by the WDT.

Note 1: See Figure 8-1 and Figure 8-2 for operation of the PWRTE bit.

2: See Figure 8-1, Figure 8-2 and Section 8.13 for operation of the Code and Data protection bits.

8.12 Power-down Mode (SLEEP)

A device may be powered down (SLEEP) and later powered up (Wake-up from SLEEP).

8.12.1 SLEEP

The Power-down mode is entered by executing the SLEEP instruction.

If enabled, the Watchdog Timer is cleared (but keeps running), the \overline{PD} bit (STATUS<3>) is cleared, the \overline{TO} bit (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For the lowest current consumption in SLEEP mode, place all I/O pins at either at VDD or VSS, with no external circuitry drawing current from the I/O pins, and disable external clocks. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSS. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}$ pin must be at a logic high level (VIHMC).

It should be noted that a RESET generated by a WDT time-out does not drive the MCLR pin low.

8.12.2 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- 1. External reset input on MCLR pin.
- 2. WDT Wake-up (if WDT was enabled).
- 3. Interrupt from RB0/INT pin, RB port change, or data EEPROM write complete.

Peripherals cannot generate interrupts during SLEEP, since no on-chip Q clocks are present.

The first event ($\overline{\text{MCLR}}$ reset) will cause a device reset. The two latter events are considered a continuation of program execution. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits can be used to determine the cause of a device reset. The $\overline{\text{PD}}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{\text{TO}}$ bit is cleared if a WDT time-out occurred (and caused wake-up).

While the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction after the state of the substant of the instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

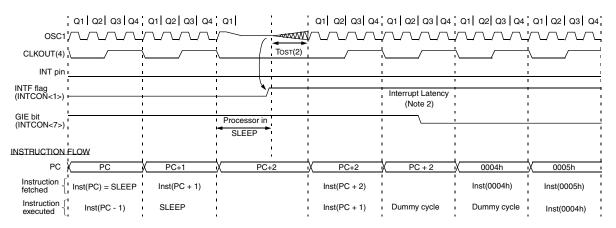


FIGURE 8-19: WAKE-UP FROM SLEEP THROUGH INTERRUPT

Note 1: XT, HS or LP oscillator mode assumed.

2: TOST = 1024TOSC (drawing not to scale) This delay will not be there for RC osc mode.

3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in these osc modes, but shown here for timing reference.

Mnemo		Description	Cycles		14-Bit	Opcode	Э	Status	Notes
Operan	ds			MSb			LSb	Affected	
		BYTE-ORIENTED FILE REG	STER OPE	RATIC	ONS				
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
		BIT-ORIENTED FILE REGIS	TER OPER	RATIO	NS				
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
		LITERAL AND CONTRO	L OPERAT	IONS					
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	レレレレ	kkkk	Z	

TABLE 9-2 PIC16FXX INSTRUCTION SET

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

PIC16F8X

NOP	No Oper	ation		
Syntax:	[label]	NOP		
Operands:	None			
Operation:	No opera	ition		
Status Affected:	None			
Encoding:	00	0000	0xx0	0000
Description:	No operati	ion.		
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	No-Opera tion	No-Opera tion	No-Operat ion
Example	NOP			

RETFIE	Return fi	rom Inter	rupt				
Syntax:	[label]	RETFIE					
Operands:	None						
Operation:	$\begin{array}{l} TOS \to F \\ 1 \to GIE \end{array}$	PC,					
Status Affected:	None						
Encoding:	0 0	0000	0000	1001			
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.						
Words:	1						
Cycles:	2						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
1st Cycle	Decode	No-Opera tion	Set the GIE bit	Pop from the Stack			
2nd Cycle	No-Operat ion	No-Opera tion	No-Opera tion	No-Operat ion			
Example	RETFIE						

After Interrupt PC = TOS GIE = 1

OPTION	Load Option Register
Syntax:	[label] OPTION
Operands:	None
Operation:	$(W) \rightarrow OPTION$
Status Affected:	None
Encoding:	00 0000 0110 0010
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code com- patibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.
Words:	1
Cycles:	1
Example	
	To maintain upward compatibility with future PIC16CXX products, do not use this instruction.



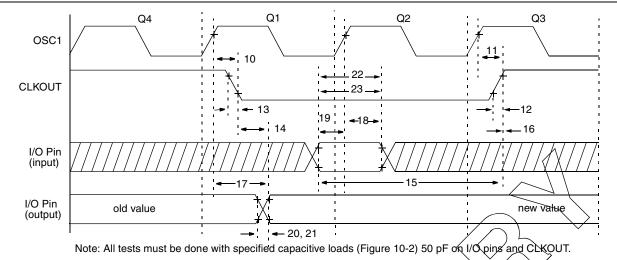


TABLE 10-4 CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteri	stic	Min	Typt	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	PIC16F8X	- /	15	30 *	ns	Note 1
10A			PIC16LF8X		15	120 *	ns	Note 1
11	TosH2ckH	OSC1↑ to CLKOUT↑	PIC16F8X	$f \neq $		30 *	ns	Note 1
11A			PIC16LF8X	$/ \neq /$	15	120 *	ns	Note 1
12	TckR	CLKOUT rise time	PIC1@F8X	$\overline{ - }$	15	30 *	ns	Note 1
12A			PIC16LF8X	\rightarrow	15	100 *	ns	Note 1
13	TckF	CLKOUT fall time	PIC16F8X	<u> </u>	15	30 *	ns	Note 1
13A			RICHOLF8X	<u> </u>	15	100 *	ns	Note 1
14	TckL2ioV	CLKOUT ↓ to Port out	valid	—		0.5TCY +20 *	ns	Note 1
15	TioV2ckH	Port in valid before	PIC16F8X	0.30TCY + 30 *		_	ns	Note 1
		CLKOUT	RIC16LF8X	0.30TCY + 80 *	—	_	ns	Note 1
16	TckH2iol	Port in hold after CLKØ	NT T	0 *		_	ns	Note 1
17	TosH2ioV	ØSC11 (Q1 cycle) to	PIC16F8X	—		125 *	ns	
		Port øut valid	PIC16LF8X	—	—	250 *	ns	
18	TosH2iol	OSC11 (Q2 cycle) to	PIC16F8X	10 *		_	ns	
	\bigcirc	Rort input invalid (I/O in hold time)	PIC16LF8X	10 *	—	—	ns	
19 <	TioV20sH	Rort input valid to	PIC16F8X	-75 *	-	_	ns	
	$\sum ($	OSC1↑ (I/O in setup time)	PIC16LF8X	-175 *	—	—	ns	
20	TioR	Port output rise time	PIC16F8X	—	10	35 *	ns	
20A	, ř		PIC16LF8X	—	10	70 *	ns	
21	TioF	Port output fall time	PIC16F8X	—	10	35 *	ns	
21A			PIC16LF8X		10	70 *	ns	
22	Tinp	INT pin high	PIC16F8X	20 *		_	ns	
22A		or low time	PIC16LF8X	55 *		_	ns	
23	Trbp	RB7:RB4 change INT	PIC16F8X	Tosc §	—	_	ns	
23A		high or low time	PIC16LF8X	Tosc §		_	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ By design

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

11.4 DC CHARACTERISTICS: PIC16CR84, PIC16CR83 (Commercial, Industrial) PIC16LCR84, PIC16LCR83 (Commercial, Industrial)

DC Characteristics All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated)Operating temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ (commercial) $-40^{\circ}C \leq TA \leq +85^{\circ}C$ (industrial)Operating voltage VDD range as described in DC specSection 11.1 and Section 11.2.				
Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
		Capacitive Loading Specs on Output Pins					\square
D100	Cosc2	OSC2 pin	_	_	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	Cio	All I/O pins and OSC2 (RC mode)	_	—	50	pF	
		Data EEPROM Memory					$ \backslash \lor \land \lor \rangle$
D120	ED	Endurance	1M	10M	—	ĘAW	25°C at 51
D121	Vdrw	VDD for read/write	VMIN	_	6.0	(v	VMN = Miximum operating
D122	TDEW	Erase/Write cycle time	—	10	2 0*	ms	

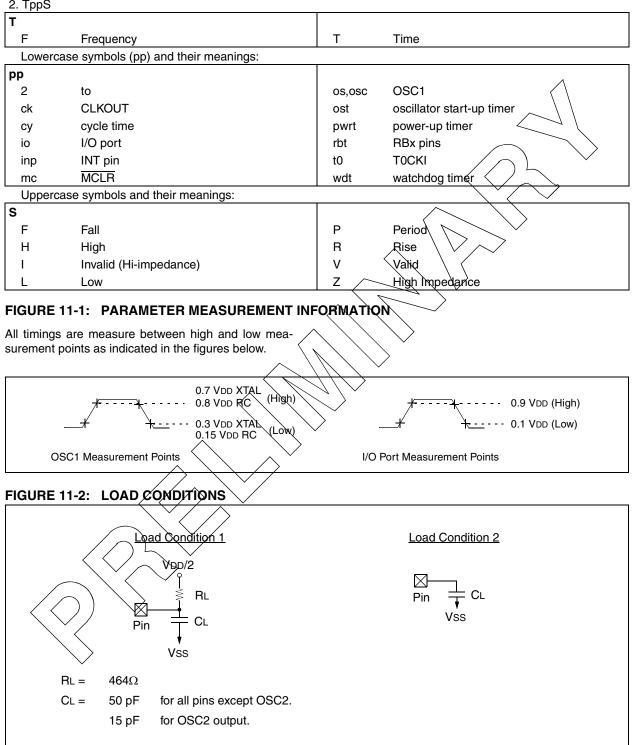
* These parameters are characterized but not tested.

 Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 11-2 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created following one of the following formats:

- 1. TppS2ppS
- 2. TppS



12.0 DC & AC CHARACTERISTICS GRAPHS/TABLES

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are guaranteed to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25° C, while 'max' or 'min' represents (mean + 3σ) and (mean - 3σ) respectively, where σ is standard deviation.

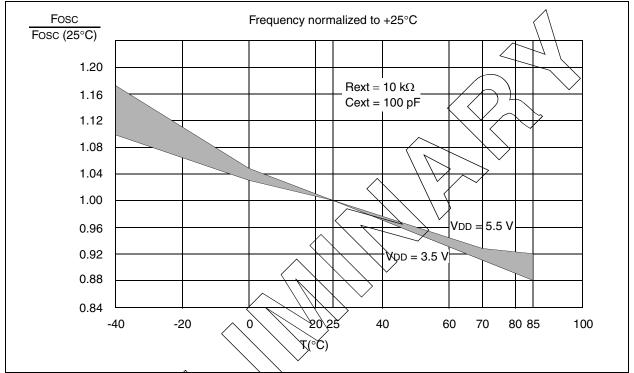
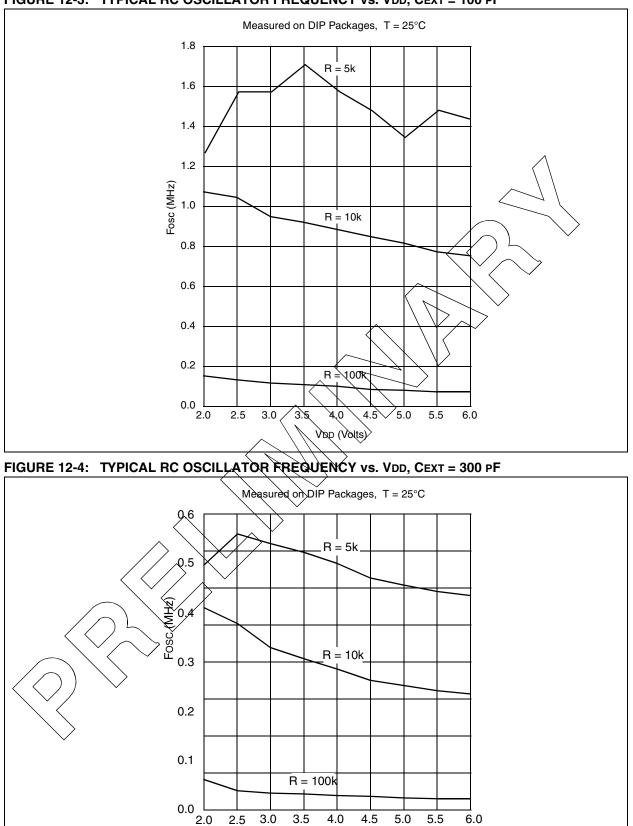


FIGURE 12-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

	RC OSCILLATOR	
TABLE 12-1	RC OSCILLA OR	FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C		
	K//		Part to Part Variation	
20 pF	5 k	4.61 MHz	± 25%	
	→ 10 k	2.66 MHz	± 24%	
	100 k	311 kHz	\pm 39%	
	5 k	1.34 MHz	± 21%	
$\langle \langle \rangle \rangle$	10 k	756 kHz	± 18%	
\square	100 k	82.8 kHz	± 28%	
300 pF	5 k	428 kHz	± 13%	
\sim	10 k	243 kHz	± 13%	
	100 k	26.2 kHz	± 23%	

* Measured on DIP packages. The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for full VDD range.



VDD (Volts)

FIGURE 12-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 100 PF

FIGURE 12-21: TYPICAL DATA MEMORY ERASE/WRITE CYCLE TIME VS. VDD

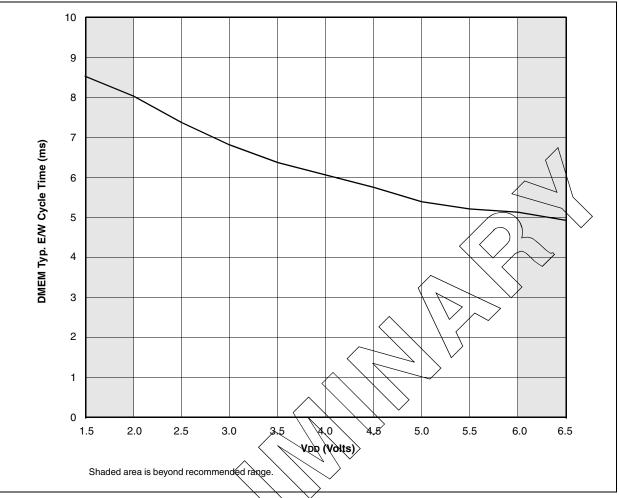


TABLE 12-2 INPUT CAPACITANCE*

Pin Name		Typical Capacitance (pF)		
	18L PDIP	18L SOIC		
PORTA	5.0	4.3		
POBTB	5.0	4.3		
	17.0	17.0		
OSCIŲCĽKĮM	4.0	3.5		
OSCZYCLKOUT	4.3	3.5		
СС тоскі	3.2	2.8		

All capacitance values are typical at 25°C. A part to part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

APPENDIX A: FEATURE IMPROVEMENTS -FROM PIC16C5X TO PIC16F8X

The following is the list of feature improvements over the PIC16C5X microcontroller family:

- 1. Instruction word length is increased to 14 bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and the register file (128 bytes now versus 32 bytes before).
- 2. A PC latch register (PCLATH) is added to handle program memory paging. PA2, PA1 and PA0 bits are removed from the status register and placed in the option register.
- 3. Data memory paging is redefined slightly. The STATUS register is modified.
- 4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions, TRIS and OPTION, are being phased out although they are kept for compatibility with PIC16C5X.
- 5. OPTION and TRIS registers are made addressable.
- 6. Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- 10. Wake up from SLEEP through interrupt is added.
- 11. Two separate timers, the Oscillator Start-up Timer (OST) and Power-up Timer (PWRT), are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change features.
- 13. T0CKI pin is also a port pin (RA4/T0CKI).
- 14. FSR is a full 8-bit register.
- 15. "In system programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, VPP, RB6 (clock) and RB7 (data in/out).

APPENDIX B: CODE COMPATIBILITY - FROM PIC16C5X TO PIC16F8X

To convert code written for PIC16C5X to PIC16F8X, the user should take the following steps:

- 1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables for reallocation.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change reset vector to 0000h.

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The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

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PIC16F8X

NOTES: